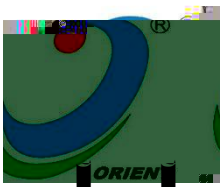


## 一级代理商：

深圳市弗瑞鑫电子有限公司

地址：深圳市宝安区西乡大道302号金源商务大厦B座三楼

frxelec

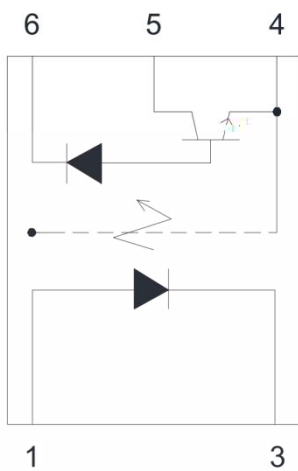


1. F a

2. I c

3. A ca Ra

4. F c a D a a



- 1. Anode
- 3. Cathode
- 4. GND
- 5. Vo (Output)
- 6. Vcc

( )	

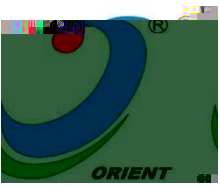


5. Ab Ma Ra (Ta=25 ) \*1

	Pa a	S b	Ra d Va	U
			~	
			~	

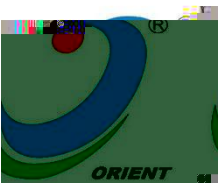
6. E c ca ca c a ac c a TA=25

Pa a	S b	M	T	Ma	U	C d



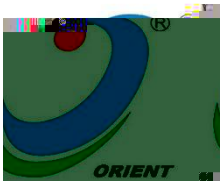
7. S c C a ac c a TA=25


020 O | .A C V5

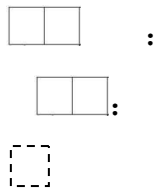
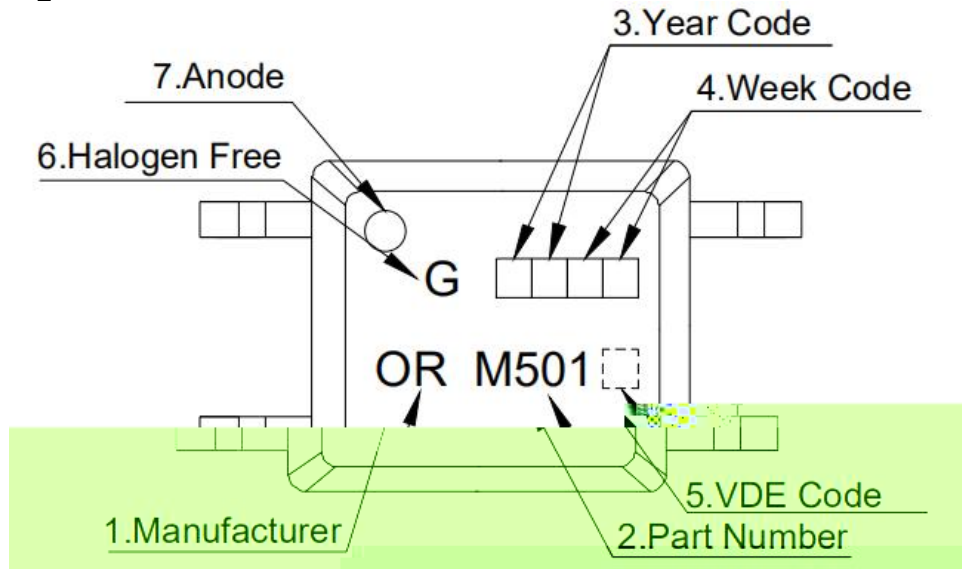


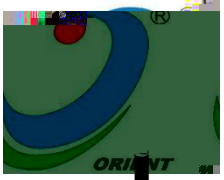
9. O d I a  
Pa I b  
**OR-M501-X-Y-Z**  
N

O	D c	Pac a



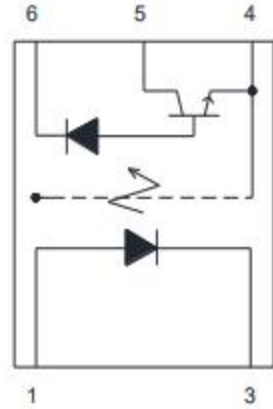
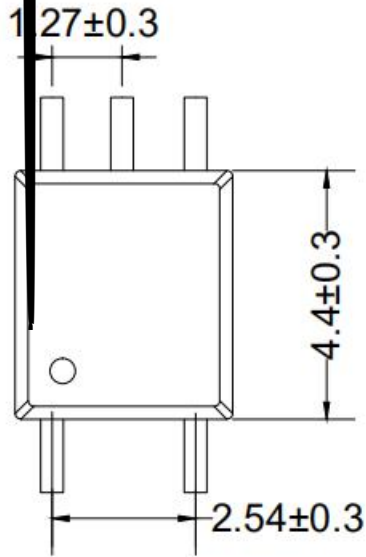
# 10. Na R



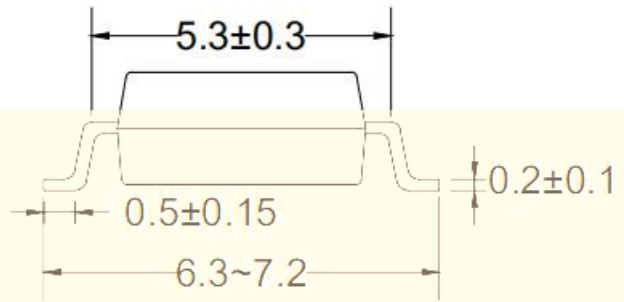
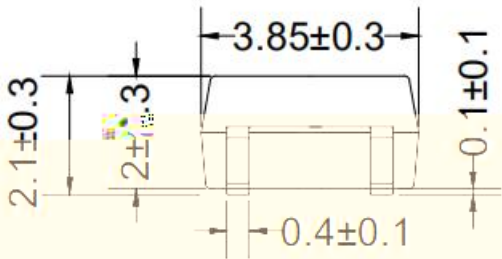


11. O D

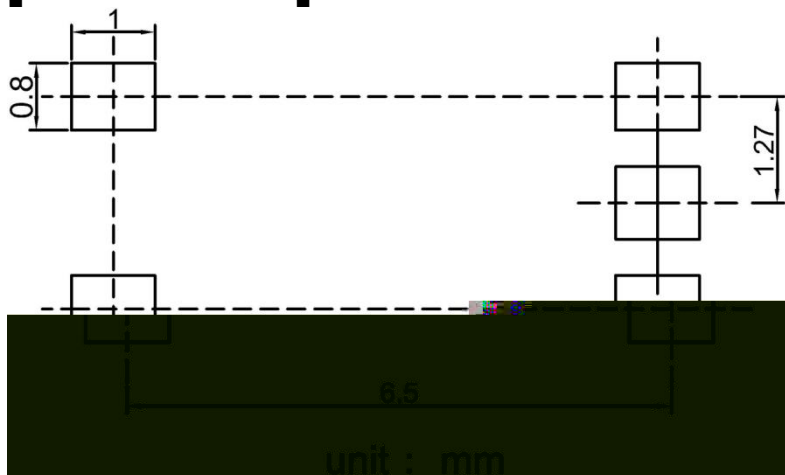
(1) OR-1501

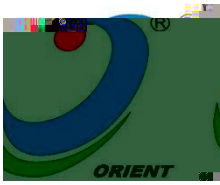


- 1. Anode
- 3. Cathode
- 4. GND
- 5. Vo(Output)
- 6. Vcc



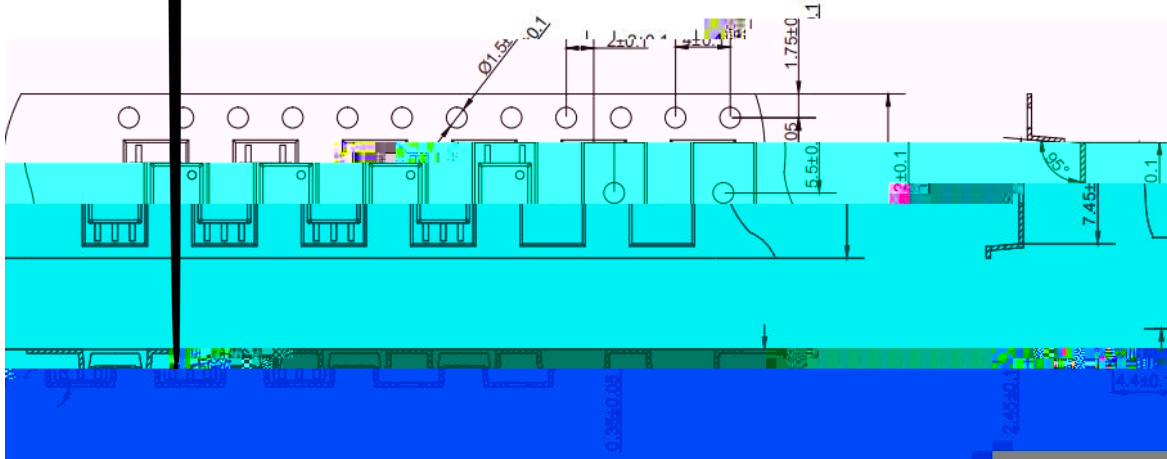
12. R c d d F P Pa (M Pad)



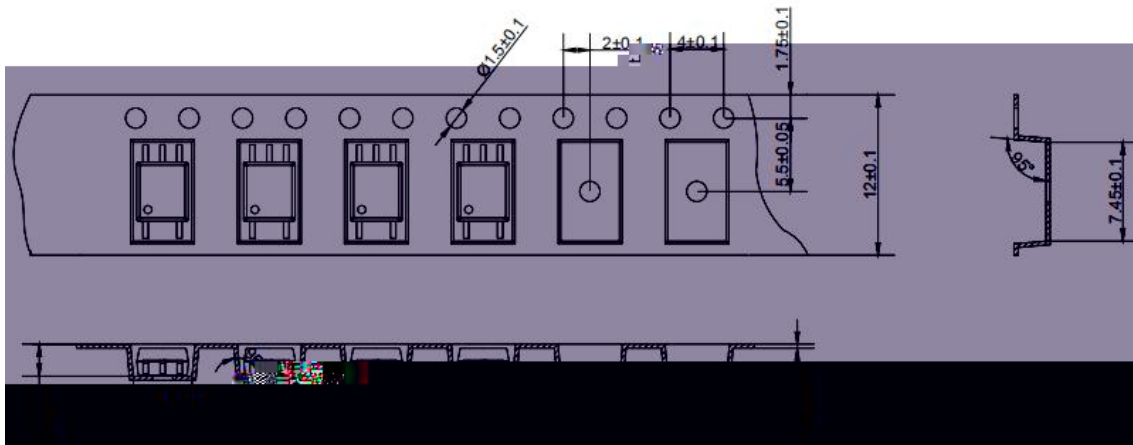


13. Та D

(1) OR-M501-TP



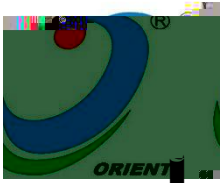
(2) OR-M501-TP1



		( )
		( )
		( )
		( )
		( )

( )	





14. Pac a D

Pac I a	

(2)Pac Lab Sa

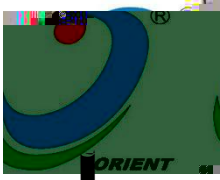
**ORIENT**  
Shenzhen Orient  
Components Co., LTD

Material Code : 120PCXXXXXX

P/N: OR-XXXXXX

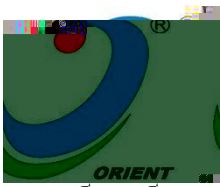
内箱码      外箱码

N :



15. R ab T

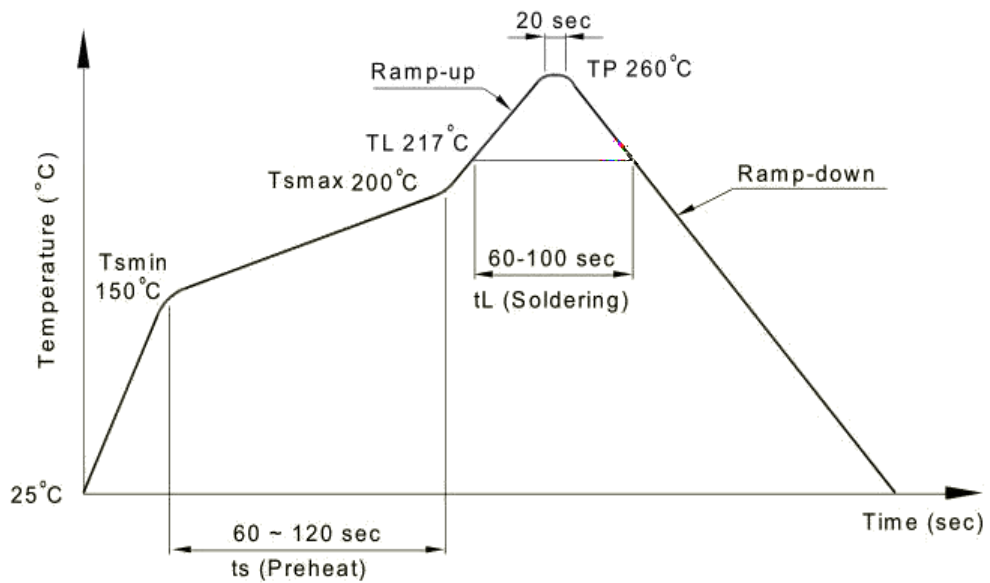
NO.	ITEMS	QTY. (Pc)	C d	P c	D c	S a d a d
	RSH 焊接热			次	炉	
	HTSL 温存储				温烤 测 仪	
	LTSL 低温存储				低温 测 仪	
	TC 温度循				冷热冲 击机	
	TS 温度冲击				冷热冲 击机	
	HTOL 温操作				温烤 测 仪、 化板	
	ESD-HB M 人体模式			次	测 仪	
	SD 可焊性			次	炉	
	温湿寿命				恒温恒湿 机, 测 仪	
	A c a 压力				压力	

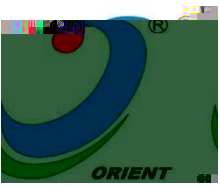


16. T a P O S d

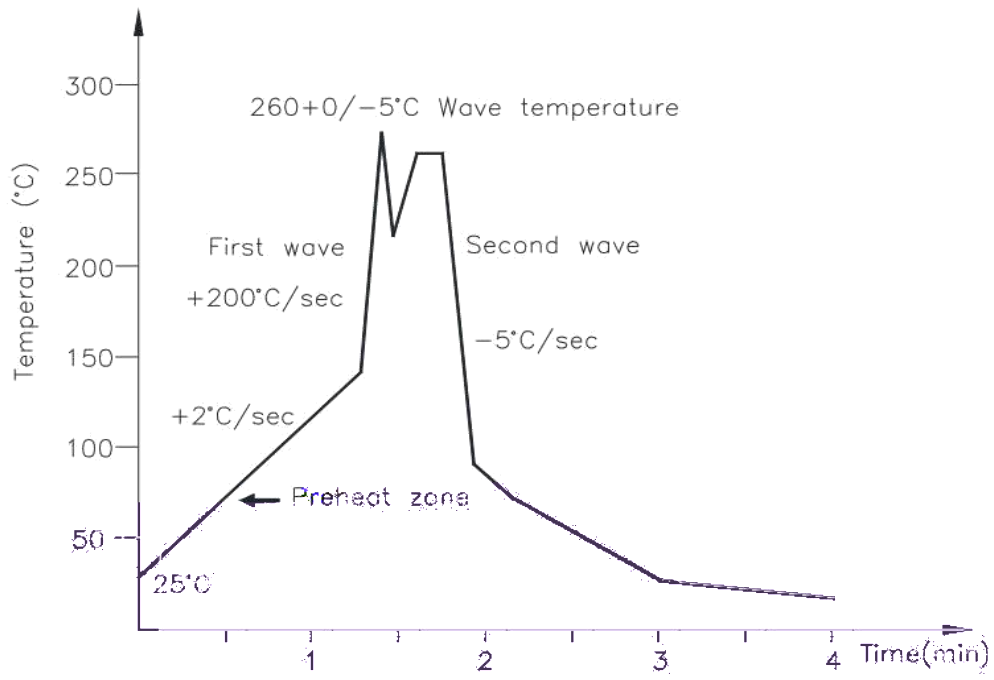
( )

P	C d



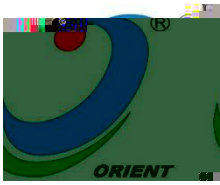


( )

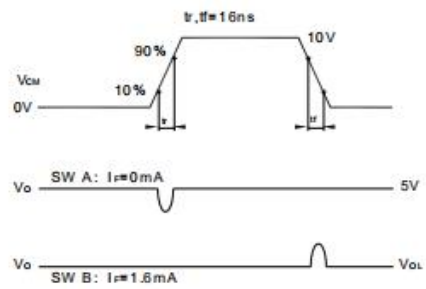
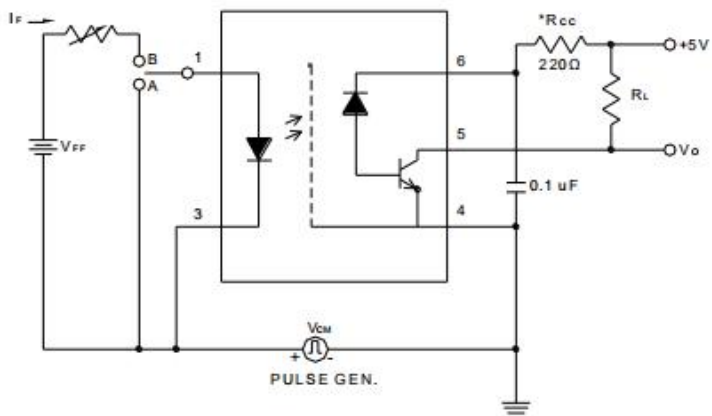
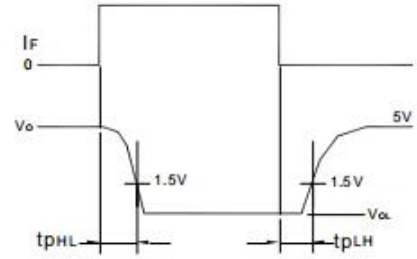
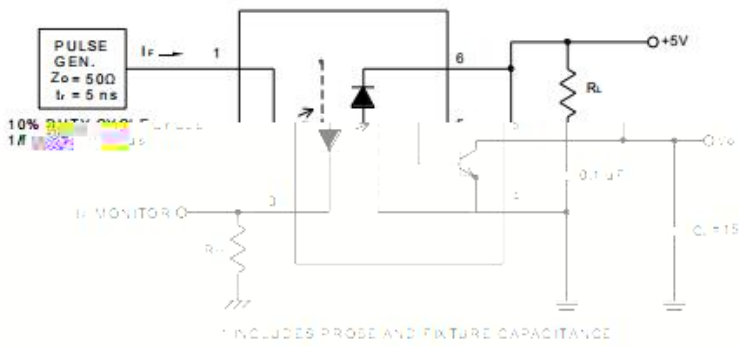



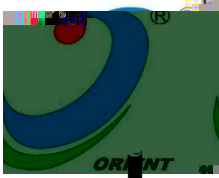
( )

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# 17. S c T T C c





C a a c c C

Figure 3: DC and pulsed transfer characteristics

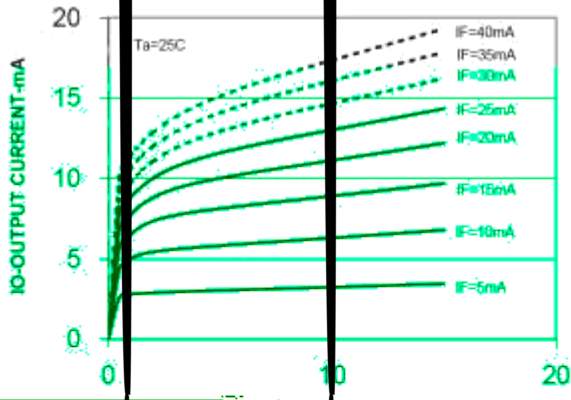


Figure 6: Current transfer ratio vs. input current

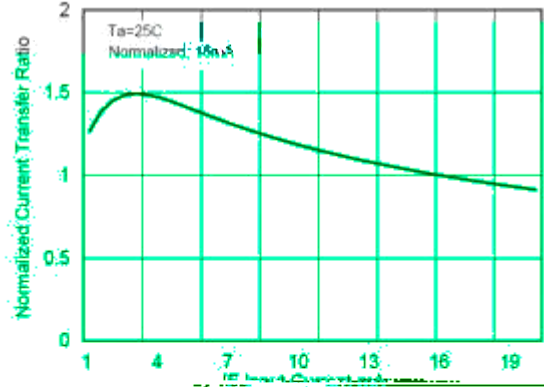


Figure 7. NORMALIZED CURRENT TRANSFER RATIO VS. AMBIENT TEMPERATURE

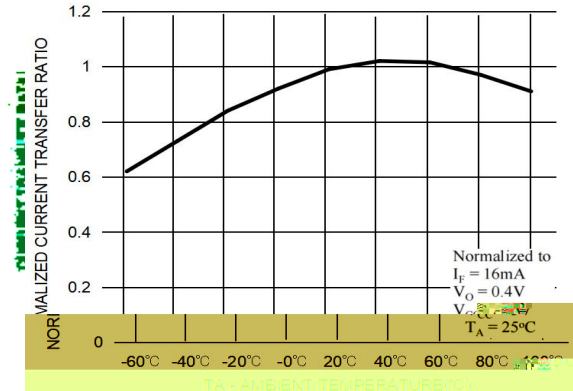


Figure 5: Logic high output current vs. temperature

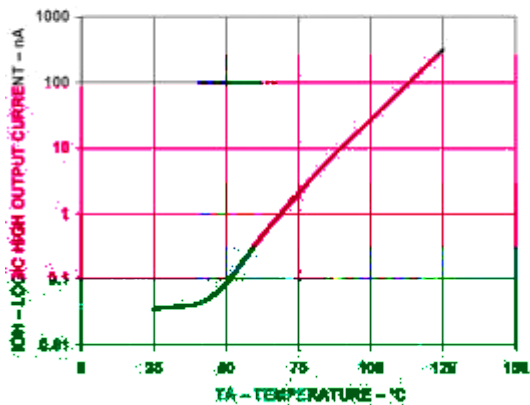
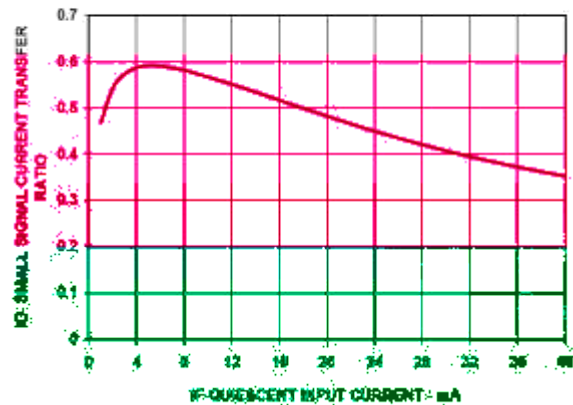


Figure 8: Small-signal current transfer ratio vs. quiescent current



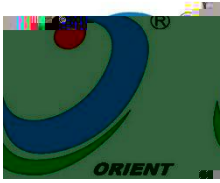


Figure 9: Propagation delay time vs. temperature

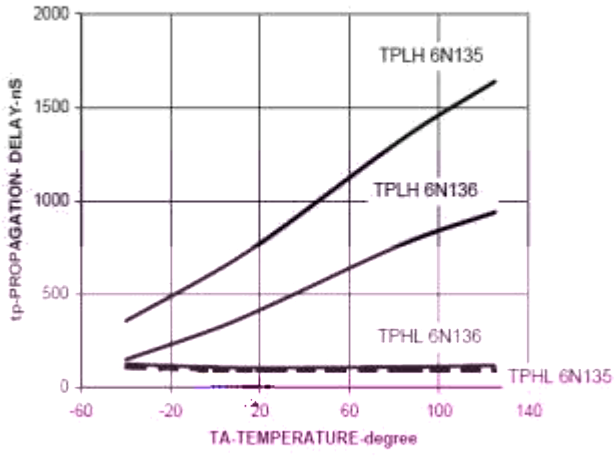


Figure 10: Propagation delay time vs. load resistance

